

Welcome to [E-XFL.COM](http://E-XFL.COM)

### What is "[Embedded - Microcontrollers](#)"?

"[Embedded - Microcontrollers](#)" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

### Applications of "[Embedded - Microcontrollers](#)"

#### Details

Product Status	Active
Core Processor	ARM7®
Core Size	16/32-Bit
Speed	44MHz
Connectivity	EBI/EMI, I <sup>2</sup> C, SPI, UART/USART
Peripherals	PLA, PWM, PSM, Temp Sensor, WDT
Number of I/O	30
Program Memory Size	62KB (31K x16)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	2K x 32
Voltage - Supply (Vcc/Vdd)	2.7V ~ 3.6V
Data Converters	A/D 10x12b; D/A 2x12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	64-LQFP
Supplier Device Package	64-LQFP (10x10)
Purchase URL	<a href="https://www.e-xfl.com/product-detail/analog-devices/aduc7024bstz62-rl">https://www.e-xfl.com/product-detail/analog-devices/aduc7024bstz62-rl</a>

DETAILED BLOCK DIAGRAM

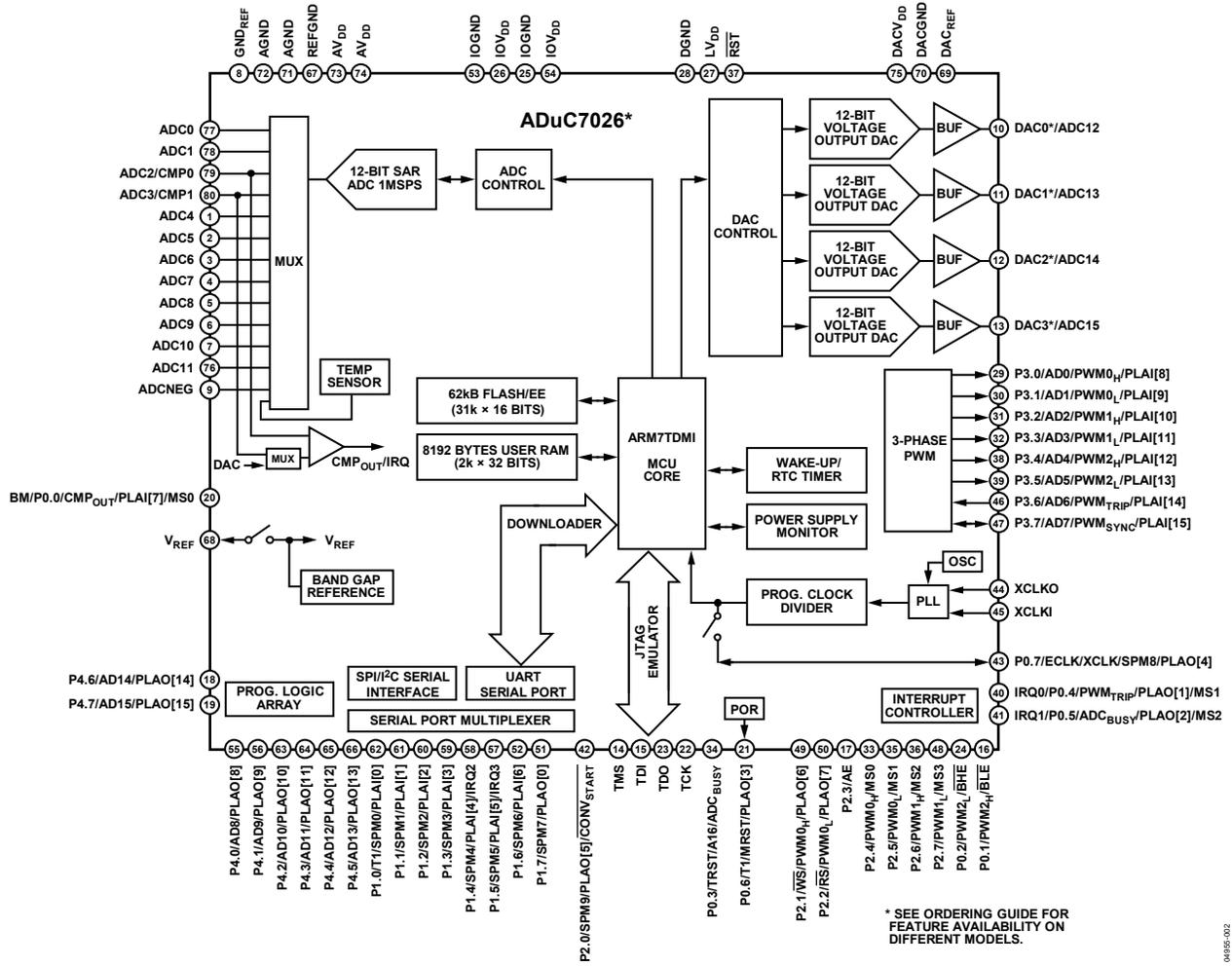


Figure 11.

04855-002

**TIMING SPECIFICATIONS**

**Table 2. External Memory Write Cycle**

Parameter	Min	Typ	Max	Unit
CLK <sup>1</sup>		UCLK		
t <sub>MS_AFTER_CLKH</sub>	0		4	ns
t <sub>ADDR_AFTER_CLKH</sub>	4		8	ns
t <sub>AE_H_AFTER_MS</sub>		½ CLK		
t <sub>AE</sub>		(XMxPAR[14:12] + 1) × CLK		
t <sub>HOLD_ADDR_AFTER_AE_L</sub>		½ CLK + (!XMxPAR[10]) × CLK		
t <sub>HOLD_ADDR_BEFORE_WR_L</sub>		(!XMxPAR[8]) × CLK		
t <sub>WR_L_AFTER_AE_L</sub>		½ CLK + (!XMxPAR[10] + !XMxPAR[8]) × CLK		
t <sub>DATA_AFTER_WR_L</sub>	8		12	ns
t <sub>WR</sub>		(XMxPAR[7:4] + 1) × CLK		
t <sub>WR_H_AFTER_CLKH</sub>	0		4	ns
t <sub>HOLD_DATA_AFTER_WR_H</sub>		(!XMxPAR[8]) × CLK		
t <sub>BEN_AFTER_AE_L</sub>		½ CLK		
t <sub>RELEASE_MS_AFTER_WR_H</sub>		(!XMxPAR[8] + 1) × CLK		

<sup>1</sup> See Table 78.

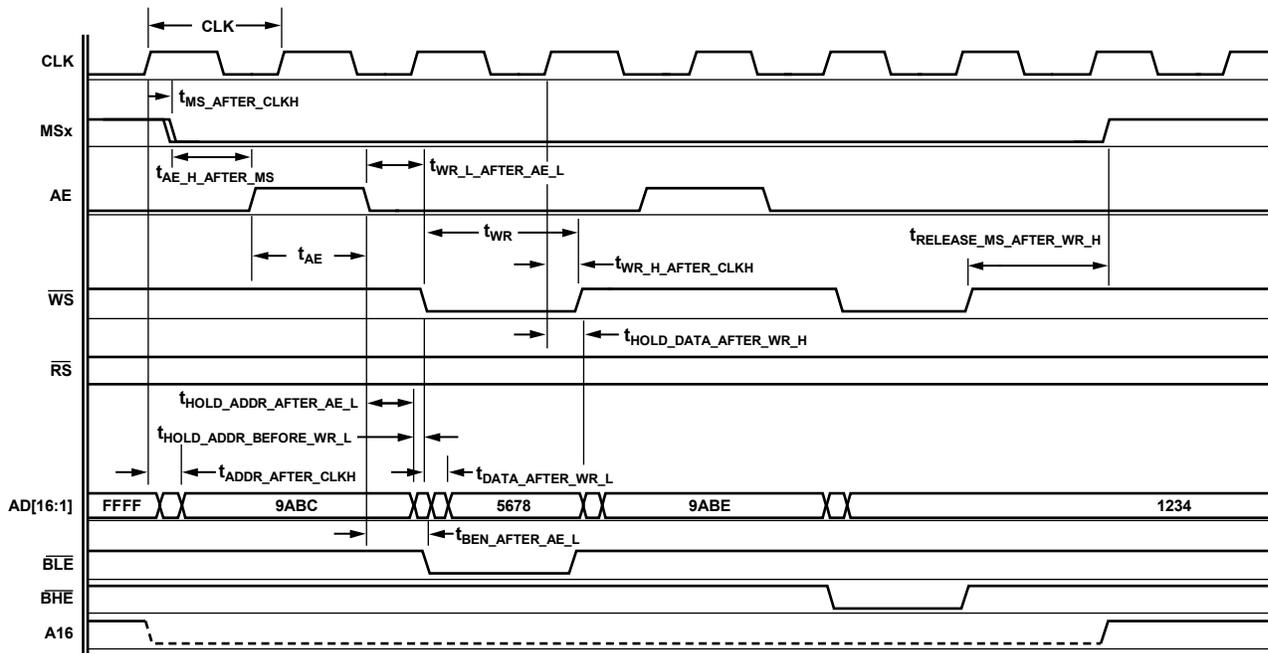


Figure 12. External Memory Write Cycle (See Table 78)

04855-052

Table 11. Pin Function Descriptions (ADuC7019/ADuC7020/ADuC7021/ADuC7022)

Pin No.			Mnemonic	Description
7019/7020	7021	7022		
38	37	36	ADC0	Single-Ended or Differential Analog Input 0.
39	38	37	ADC1	Single-Ended or Differential Analog Input 1.
40	39	38	ADC2/CMP0	Single-Ended or Differential Analog Input 2/Comparator Positive Input.
1	40	39	ADC3/CMP1	Single-Ended or Differential Analog Input 3 (Buffered Input on ADuC7019)/Comparator Negative Input.
2	1	40	ADC4	Single-Ended or Differential Analog Input 4.
–	2	1	ADC5	Single-Ended or Differential Analog Input 5.
–	3	2	ADC6	Single-Ended or Differential Analog Input 6.
–	4	3	ADC7	Single-Ended or Differential Analog Input 7.
–	–	4	ADC8	Single-Ended or Differential Analog Input 8.
–	–	5	ADC9	Single-Ended or Differential Analog Input 9.
3	5	6	GND <sub>REF</sub>	Ground Voltage Reference for the ADC. For optimal performance, the analog power supply should be separated from IOGND and DGND.
4	6	–	DAC0/ADC12	DAC0 Voltage Output/Single-Ended or Differential Analog Input 12.
5	7	–	DAC1/ADC13	DAC1 Voltage Output/Single-Ended or Differential Analog Input 13.
6	–	–	DAC2/ADC14	DAC2 Voltage Output/Single-Ended or Differential Analog Input 14.
7	–	–	DAC3/ADC15	DAC3 Voltage Output on ADuC7020. On the ADuC7019, a 10 nF capacitor must be connected between this pin and AGND/Single-Ended or Differential Analog Input 15 (see Figure 53).
8	8	7	TMS	Test Mode Select, JTAG Test Port Input. Debug and download access. This pin has an internal pull-up resistor to IOV <sub>DD</sub> . In some cases, an external pull-up resistor (~100K) is also required to ensure that the part does not enter an erroneous state.
9	9	8	TDI	Test Data In, JTAG Test Port Input. Debug and download access.
10	10	9	BM/P0.0/CMP <sub>OUT</sub> /PLAI[7]	Multifunction I/O Pin. Boot Mode (BM). The ADuC7019/20/21/22 enter serial download mode if BM is low at reset and execute code if BM is pulled high at reset through a 1 k $\Omega$ resistor/General-Purpose Input and Output Port 0.0/Voltage Comparator Output/Programmable Logic Array Input Element 7.
11	11	10	P0.6/T1/MRST/PLAO[3]	Multifunction Pin. Driven low after reset. General-Purpose Output Port 0.6/Timer1 Input/Power-On Reset Output/Programmable Logic Array Output Element 3.
12	12	11	TCK	Test Clock, JTAG Test Port Input. Debug and download access. This pin has an internal pull-up resistor to IOV <sub>DD</sub> . In some cases an external pull-up resistor (~100K) is also required to ensure that the part does not enter an erroneous state.
13	13	12	TDO	Test Data Out, JTAG Test Port Output. Debug and download access.
14	14	13	IOGND	Ground for GPIO (see Table 78). Typically connected to DGND.
15	15	14	IOV <sub>DD</sub>	3.3 V Supply for GPIO (see Table 78) and Input of the On-Chip Voltage Regulator.
16	16	15	LV <sub>DD</sub>	2.6 V Output of the On-Chip Voltage Regulator. This output must be connected to a 0.47 $\mu$ F capacitor to DGND only.
17	17	16	DGND	Ground for Core Logic.
18	18	17	P0.3/TRST/ADC <sub>BUSY</sub>	General-Purpose Input and Output Port 0.3/Test Reset, JTAG Test Port Input/ADC <sub>BUSY</sub> Signal Output.
19	19	18	$\overline{\text{RST}}$	Reset Input, Active Low.
20	20	19	IRQ0/P0.4/PWM <sub>TRIP</sub> /PLAO[1]	Multifunction I/O Pin. External Interrupt Request 0, Active High/General-Purpose Input and Output Port 0.4/PWM Trip External Input/Programmable Logic Array Output Element 1.
21	21	20	IRQ1/P0.5/ADC <sub>BUSY</sub> /PLAO[2]	Multifunction I/O Pin. External Interrupt Request 1, Active High/General-Purpose Input and Output Port 0.5/ADC <sub>BUSY</sub> Signal Output/Programmable Logic Array Output Element 2.

Table 12. Pin Function Descriptions (ADuC7024/ADuC7025 64-Lead LFCSP\_VQ and 64-Lead LQFP)

Pin No.	Mnemonic	Description
1	ADC4	Single-Ended or Differential Analog Input 4.
2	ADC5	Single-Ended or Differential Analog Input 5.
3	ADC6	Single-Ended or Differential Analog Input 6.
4	ADC7	Single-Ended or Differential Analog Input 7.
5	ADC8	Single-Ended or Differential Analog Input 8.
6	ADC9	Single-Ended or Differential Analog Input 9.
7	GND <sub>REF</sub>	Ground Voltage Reference for the ADC. For optimal performance, the analog power supply should be separated from IOGND and DGND.
8	ADCNEG	Bias Point or Negative Analog Input of the ADC in Pseudo Differential Mode. Must be connected to the ground of the signal to convert. This bias point must be between 0 V and 1 V.
9	DAC0/ADC12	DAC0 Voltage Output/Single-Ended or Differential Analog Input 12. DAC outputs are not present on the ADuC7025.
10	DAC1/ADC13	DAC1 Voltage Output/Single-Ended or Differential Analog Input 13. DAC outputs are not present on the ADuC7025.
11	TMS	JTAG Test Port Input, Test Mode Select. Debug and download access.
12	TDI	JTAG Test Port Input, Test Data In. Debug and download access
13	P4.6/PLAO[14]	General-Purpose Input and Output Port 4.6/Programmable Logic Array Output Element 14.
14	P4.7/PLAO[15]	General-Purpose Input and Output Port 4.7/Programmable Logic Array Output Element 15.
15	BM/P0.0/CMP <sub>OUT</sub> /PLAI[7]	Multifunction I/O Pin. Boot mode. The ADuC7024/ADuC7025 enter download mode if BM is low at reset and execute code if BM is pulled high at reset through a 1 k $\Omega$ resistor/General-Purpose Input and Output Port 0.0/Voltage Comparator Output/Programmable Logic Array Input Element 7.
16	P0.6/T1/MRST/PLAO[3]	Multifunction Pin, Driven Low After Reset. General-Purpose Output Port 0.6/Timer1 Input/Power-On Reset Output/Programmable Logic Array Output Element 3.
17	TCK	JTAG Test Port Input, Test Clock. Debug and download access.
18	TDO	JTAG Test Port Output, Test Data Out. Debug and download access.
19	IOGND	Ground for GPIO (see Table 78). Typically connected to DGND.
20	IOV <sub>DD</sub>	3.3 V Supply for GPIO (see Table 78) and Input of the On-Chip Voltage Regulator.
21	LV <sub>DD</sub>	2.6 V Output of the On-Chip Voltage Regulator. This output must be connected to a 0.47 $\mu$ F capacitor to DGND only.
22	DGND	Ground for Core Logic.
23	P3.0/PWM0 <sub>H</sub> /PLAI[8]	General-Purpose Input and Output Port 3.0/PWM Phase 0 High-Side Output/Programmable Logic Array Input Element 8.
24	P3.1/PWM0 <sub>L</sub> /PLAI[9]	General-Purpose Input and Output Port 3.1/PWM Phase 0 Low-Side Output/Programmable Logic Array Input Element 9.
25	P3.2/PWM1 <sub>H</sub> /PLAI[10]	General-Purpose Input and Output Port 3.2/PWM Phase 1 High-Side Output/Programmable Logic Array Input Element 10.
26	P3.3/PWM1 <sub>L</sub> /PLAI[11]	General-Purpose Input and Output Port 3.3/PWM Phase 1 Low-Side Output/Programmable Logic Array Input Element 11.
27	P0.3/TRST/ADC <sub>BUSY</sub>	General-Purpose Input and Output Port 0.3/JTAG Test Port Input, Test Reset/ADC <sub>BUSY</sub> Signal Output.
28	R <sub>ST</sub>	Reset Input, Active Low.
29	P3.4/PWM2 <sub>H</sub> /PLAI[12]	General-Purpose Input and Output Port 3.4/PWM Phase 2 High-Side Output/Programmable Logic Array Input 12.
30	P3.5/PWM2 <sub>L</sub> /PLAI[13]	General-Purpose Input and Output Port 3.5/PWM Phase 2 Low-Side Output/Programmable Logic Array Input Element 13.
31	IRQ0/P0.4/PWM <sub>TRIP</sub> /PLAO[1]	Multifunction I/O Pin. External Interrupt Request 0, Active High/General-Purpose Input and Output Port 0.4/PWM Trip External Input/Programmable Logic Array Output Element 1.
32	IRQ1/P0.5/ADC <sub>BUSY</sub> /PLAO[2]	Multifunction I/O Pin. External Interrupt Request 1, Active High/General-Purpose Input and Output Port 0.5/ADC <sub>BUSY</sub> Signal Output/Programmable Logic Array Output Element 2.
33	P2.0/SPM9/PLAO[5]/CONV <sub>START</sub>	Serial Port Multiplexed. General-Purpose Input and Output Port 2.0/UART/Programmable Logic Array Output Element 5/Start Conversion Input Signal for ADC.
34	P0.7/ECLK/XCLK/SPM8/PLAO[4]	Serial Port Multiplexed. General-Purpose Input and Output Port 0.7/Output for External Clock Signal/Input to the Internal Clock Generator Circuits/UART/Programmable Logic Array Output Element 4.
35	XCLKO	Output from the Crystal Oscillator Inverter.
36	XCLKI	Input to the Crystal Oscillator Inverter and Input to the Internal Clock Generator Circuits.

## TERMINOLOGY

### ADC SPECIFICATIONS

#### Integral Nonlinearity (INL)

The maximum deviation of any code from a straight line passing through the endpoints of the ADC transfer function. The endpoints of the transfer function are zero scale, a point  $\frac{1}{2}$  LSB below the first code transition, and full scale, a point  $\frac{1}{2}$  LSB above the last code transition.

#### Differential Nonlinearity (DNL)

The difference between the measured and the ideal 1 LSB change between any two adjacent codes in the ADC.

#### Offset Error

The deviation of the first code transition (0000 . . . 000) to (0000 . . . 001) from the ideal, that is,  $+\frac{1}{2}$  LSB.

#### Gain Error

The deviation of the last code transition from the ideal AIN voltage (full scale – 1.5 LSB) after the offset error has been adjusted out.

#### Signal to (Noise + Distortion) Ratio (SINAD)

The measured ratio of signal to (noise + distortion) at the output of the ADC. The signal is the rms amplitude of the fundamental. Noise is the rms sum of all nonfundamental signals up to half the sampling frequency ( $f_s/2$ ), excluding dc.

The ratio is dependent upon the number of quantization levels in the digitization process; the more levels, the smaller the quantization noise.

The theoretical signal to (noise + distortion) ratio for an ideal N-bit converter with a sine wave input is given by

$$\text{Signal to (Noise + Distortion)} = (6.02 N + 1.76) \text{ dB}$$

Thus, for a 12-bit converter, this is 74 dB.

#### Total Harmonic Distortion (THD)

The ratio of the rms sum of the harmonics to the fundamental.

### DAC SPECIFICATIONS

#### Relative Accuracy

Otherwise known as endpoint linearity, relative accuracy is a measure of the maximum deviation from a straight line passing through the endpoints of the DAC transfer function. It is measured after adjusting for zero error and full-scale error.

#### Voltage Output Settling Time

The amount of time it takes the output to settle to within a 1 LSB level for a full-scale input change.

More information relative to the programmer's model and the ARM7TDMI core architecture can be found in the following materials from ARM:

- DDI0029G, *ARM7TDMI Technical Reference Manual*
- DDI-0100, *ARM Architecture Reference Manual*

## INTERRUPT LATENCY

The worst-case latency for a fast interrupt request (FIQ) consists of the following:

- The longest time the request can take to pass through the synchronizer
- The time for the longest instruction to complete (the longest instruction is an LDM) that loads all the registers including the PC
- The time for the data abort entry
- The time for FIQ entry

At the end of this time, the ARM7TDMI executes the instruction at 0x1C (FIQ interrupt vector address). The maximum total time is 50 processor cycles, which is just under 1.2  $\mu$ s in a system using a continuous 41.78 MHz processor clock.

The maximum interrupt request (IRQ) latency calculation is similar but must allow for the fact that FIQ has higher priority and may delay entry into the IRQ handling routine for an arbitrary length of time. This time can be reduced to 42 cycles if the LDM command is not used. Some compilers have an option to compile without using this command. Another option is to run the part in thumb mode where the time is reduced to 22 cycles.

The minimum latency for FIQ or IRQ interrupts is a total of five cycles, which consist of the shortest time the request can take through the synchronizer plus the time to enter the exception mode.

Note that the ARM7TDMI always runs in ARM (32-bit) mode when in privileged modes, for example, when executing interrupt service routines.

## MEMORY ORGANIZATION

The ADuC7019/20/21/22/24/25/26/27/28/29 incorporate two separate blocks of memory: 8 kB of SRAM and 64 kB of on-chip Flash/EE memory. The 62 kB of on-chip Flash/EE memory is available to the user, and the remaining 2 kB are reserved for the factory-configured boot page. These two blocks are mapped as shown in Figure 45.

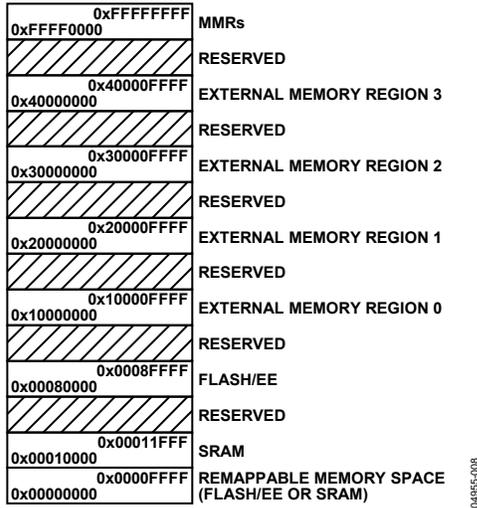


Figure 45. Physical Memory Map

Note that by default, after a reset, the Flash/EE memory is mirrored at Address 0x00000000. It is possible to remap the SRAM at Address 0x00000000 by clearing Bit 0 of the REMAP MMR. This remap function is described in more detail in the Flash/EE Memory section.

### MEMORY ACCESS

The ARM7 core sees memory as a linear array of a 2<sup>32</sup> byte location where the different blocks of memory are mapped as outlined in Figure 45.

The ADuC7019/20/21/22/24/25/26/27/28/29 memory organizations are configured in little endian format, which means that the least significant byte is located in the lowest byte address, and the most significant byte is in the highest byte address.

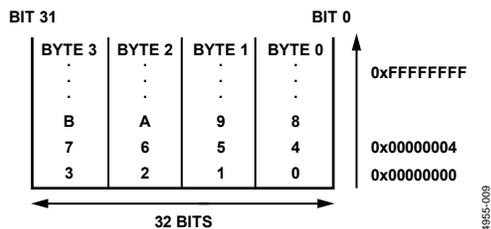


Figure 46. Little Endian Format

### FLASH/EE MEMORY

The total 64 kB of Flash/EE memory is organized as 32 k × 16 bits; 31 k × 16 bits is user space and 1 k × 16 bits is reserved for the on-chip kernel. The page size of this Flash/EE memory is 512 bytes.

Sixty-two kilobytes of Flash/EE memory are available to the user as code and nonvolatile data memory. There is no distinction between data and program because ARM code shares the same space. The real width of the Flash/EE memory is 16 bits, which means that in ARM mode (32-bit instruction), two accesses to the Flash/EE are necessary for each instruction fetch. It is therefore recommended to use thumb mode when executing from Flash/EE memory for optimum access speed. The maximum access speed for the Flash/EE memory is 41.78 MHz in thumb mode and 20.89 MHz in full ARM mode. More details about Flash/EE access time are outlined in the Execution Time from SRAM and Flash/EE section.

### SRAM

Eight kilobytes of SRAM are available to the user, organized as 2 k × 32 bits, that is, two words. ARM code can run directly from SRAM at 41.78 MHz, given that the SRAM array is configured as a 32-bit wide memory array. More details about SRAM access time are outlined in the Execution Time from SRAM and Flash/EE section.

### MEMORY MAPPED REGISTERS

The memory mapped register (MMR) space is mapped into the upper two pages of the memory array and accessed by indirect addressing through the ARM7 banked registers.

The MMR space provides an interface between the CPU and all on-chip peripherals. All registers, except the core registers, reside in the MMR area. All shaded locations shown in Figure 47 are unoccupied or reserved locations and should not be accessed by user software. Table 16 shows the full MMR memory map.

The access time for reading from or writing to an MMR depends on the advanced microcontroller bus architecture (AMBA) bus used to access the peripheral. The processor has two AMBA buses: the advanced high performance bus (AHB) used for system modules and the advanced peripheral bus (APB) used for lower performance peripheral. Access to the AHB is one cycle, and access to the APB is two cycles. All peripherals on the ADuC7019/20/21/22/24/25/26/27/28/29 are on the APB except the Flash/EE memory, the GPIOs (see Table 78), and the PWM.

Address	Name	Byte	Access Type	Default Value	Page
Reference Address Base = 0xFFFF0480					
0x048C	REFCON	1	R/W	0x00	50

## ADC Address Base = 0xFFFF0500

0x0500	ADCCON	2	R/W	0x0600	46
0x0504	ADCCP	1	R/W	0x00	47
0x0508	ADCCN	1	R/W	0x01	47
0x050C	ADCSTA	1	R	0x00	48
0x0510	ADCDAT	4	R	0x00000000	48
0x0514	ADCRST	1	R/W	0x00	48
0x0530	ADCGN	2	R/W	0x0200	48
0x0534	ADCOF	2	R/W	0x0200	48

## DAC Address Base = 0xFFFF0600

0x0600	DAC0CON	1	R/W	0x00	56
0x0604	DAC0DAT	4	R/W	0x00000000	56
0x0608	DAC1CON	1	R/W	0x00	56
0x060C	DAC1DAT	4	R/W	0x00000000	56
0x0610	DAC2CON	1	R/W	0x00	56
0x0614	DAC2DAT	4	R/W	0x00000000	56
0x0618	DAC3CON	1	R/W	0x00	56
0x061C	DAC3DAT	4	R/W	0x00000000	56

## UART Base Address = 0xFFFF0700

0x0700	COMTX	1	R/W	0x00	71
	COMRX	1	R	0x00	71
	COMDIV0	1	R/W	0x00	71
0x0704	COMIEN0	1	R/W	0x00	71
	COMDIV1	1	R/W	0x00	72
0x0708	COMIID0	1	R	0x01	72
0x070C	COMCON0	1	R/W	0x00	72
0x0710	COMCON1	1	R/W	0x00	72
0x0714	COMSTAO	1	R	0x60	72
0x0718	COMSTA1	1	R	0x00	73
0x071C	COMSCR	1	R/W	0x00	73
0x0720	COMIEN1	1	R/W	0x04	73
0x0724	COMIID1	1	R	0x01	73
0x0728	COMADR	1	R/W	0xAA	74
0x072C	COMDIV2	2	R/W	0x0000	73

Address	Name	Byte	Access Type	Default Value	Page
I2C0 Base Address = 0xFFFF0800					
0x0800	I2C0MSTA	1	R/W	0x00	76
0x0804	I2C0SSTA	1	R	0x01	76
0x0808	I2C0SRX	1	R	0x00	77
0x080C	I2C0STX	1	W	0x00	77
0x0810	I2C0MRX	1	R	0x00	77
0x0814	I2C0MTX	1	W	0x00	77
0x0818	I2C0CNT	1	R/W	0x00	77
0x081C	I2C0ADR	1	R/W	0x00	77
0x0824	I2C0BYTE	1	R/W	0x00	77
0x0828	I2C0ALT	1	R/W	0x00	78
0x082C	I2C0CFG	1	R/W	0x00	78
0x0830	I2C0DIV	2	R/W	0x1F1F	79
0x0838	I2C0ID0	1	R/W	0x00	79
0x083C	I2C0ID1	1	R/W	0x00	79
0x0840	I2C0ID2	1	R/W	0x00	79
0x0844	I2C0ID3	1	R/W	0x00	79
0x0848	I2C0CCNT	1	R/W	0x01	79
0x084C	I2C0FSTA	2	R/W	0x0000	79

## I2C1 Base Address = 0xFFFF0900

0x0900	I2C1MSTA	1	R/W	0x00	76
0x0904	I2C1SSTA	1	R	0x01	76
0x0908	I2C1SRX	1	R	0x00	77
0x090C	I2C1STX	1	W	0x00	77
0x0910	I2C1MRX	1	R	0x00	77
0x0914	I2C1MTX	1	W	0x00	77
0x0918	I2C1CNT	1	R/W	0x00	77
0x091C	I2C1ADR	1	R/W	0x00	77
0x0924	I2C1BYTE	1	R/W	0x00	77
0x0928	I2C1ALT	1	R/W	0x00	78
0x092C	I2C1CFG	1	R/W	0x00	78
0x0930	I2C1DIV	2	R/W	0x1F1F	79
0x0938	I2C1ID0	1	R/W	0x00	79
0x093C	I2C1ID1	1	R/W	0x00	79
0x0940	I2C1ID2	1	R/W	0x00	79
0x0944	I2C1ID3	1	R/W	0x00	79
0x0948	I2C1CCNT	1	R/W	0x01	79
0x094C	I2C1FSTA	2	R/W	0x0000	79

## SPI Base Address = 0xFFFF0A00

0x0A00	SPISTA	1	R	0x00	75
0x0A04	SPIRX	1	R	0x00	75
0x0A08	SPLITX	1	W	0x00	75
0x0A0C	SPIDIV	1	R/W	0x1B	75
0x0A10	SPICON	2	R/W	0x0000	75

**EXECUTION TIME FROM SRAM AND FLASH/EE**

**Execution from SRAM**

Fetching instructions from SRAM takes one clock cycle; the access time of the SRAM is 2 ns, and a clock cycle is 22 ns minimum. However, if the instruction involves reading or writing data to memory, one extra cycle must be added if the data is in SRAM (or three cycles if the data is in Flash/EE): one cycle to execute the instruction, and two cycles to get the 32-bit data from Flash/EE. A control flow instruction (a branch instruction, for example) takes one cycle to fetch but also takes two cycles to fill the pipeline with the new instructions.

**Execution from Flash/EE**

Because the Flash/EE width is 16 bits and access time for 16-bit words is 22 ns, execution from Flash/EE cannot be done in one cycle (as can be done from SRAM when the CD Bit = 0). Also, some dead times are needed before accessing data for any value of the CD bit.

In ARM mode, where instructions are 32 bits, two cycles are needed to fetch any instruction when CD = 0. In thumb mode, where instructions are 16 bits, one cycle is needed to fetch any instruction.

Timing is identical in both modes when executing instructions that involve using the Flash/EE for data memory. If the instruction to be executed is a control flow instruction, an extra cycle is needed to decode the new address of the program counter, and then four cycles are needed to fill the pipeline. A data-processing instruction involving only the core register does not require any extra clock cycles. However, if it involves data in Flash/EE, an extra clock cycle is needed to decode the address of the data, and two cycles are needed to get the 32-bit data from Flash/EE. An extra cycle must also be added before fetching another instruction. Data transfer instructions are more complex and are summarized in Table 43.

**Table 43. Execution Cycles in ARM/Thumb Mode**

Instructions	Fetch Cycles	Dead Time	Data Access	Dead Time
LD <sup>1</sup>	2/1	1	2	1
LDH	2/1	1	1	1
LDM/PUSH	2/1	N <sup>2</sup>	2 × N <sup>2</sup>	N <sup>1</sup>
STR <sup>1</sup>	2/1	1	2 × 20 ns	1
STRH	2/1	1	20 ns	1
STRM/POP	2/1	N <sup>1</sup>	2 × N × 20 ns <sup>1</sup>	N <sup>1</sup>

<sup>1</sup>The SWAP instruction combines an LD and STR instruction with only one fetch, giving a total of eight cycles + 40 ns.

<sup>2</sup>N is the amount of data to load or store in the multiple load/store instruction (1 < N ≤ 16).

**RESET AND REMAP**

The ARM exception vectors are all situated at the bottom of the memory array, from Address 0x00000000 to Address 0x00000020, as shown in Figure 62.

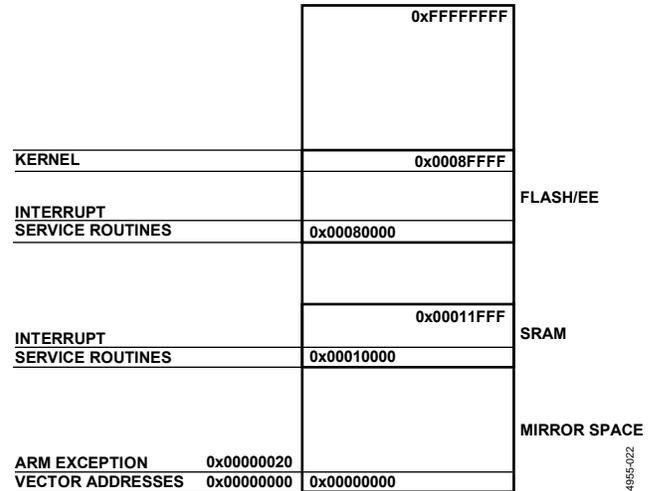


Figure 62. Remap for Exception Execution

By default, and after any reset, the Flash/EE is mirrored at the bottom of the memory array. The remap function allows the programmer to mirror the SRAM at the bottom of the memory array, which facilitates execution of exception routines from SRAM instead of from Flash/EE. This means exceptions are executed twice as fast, being executed in 32-bit ARM mode with 32-bit wide SRAM instead of 16-bit wide Flash/EE memory.

**Remap Operation**

When a reset occurs on the ADuC7019/20/21/22/24/25/26/27/28/29, execution automatically starts in the factory-programmed, internal configuration code. This kernel is hidden and cannot be accessed by user code. If the part is in normal mode (the BM pin is high), it executes the power-on configuration routine of the kernel and then jumps to the reset vector address, 0x00000000, to execute the user's reset exception routine.

Because the Flash/EE is mirrored at the bottom of the memory array at reset, the reset interrupt routine must always be written in Flash/EE.

The remap is done from Flash/EE by setting Bit 0 of the REMAP register. Caution must be taken to execute this command from Flash/EE, above Address 0x00080020, and not from the bottom of the array because this is replaced by the SRAM.

This operation is reversible. The Flash/EE can be remapped at Address 0x00000000 by clearing Bit 0 of the REMAP MMR. Caution must again be taken to execute the remap function from outside the mirrored area. Any type of reset remaps the Flash/EE memory at the bottom of the array.

**Reset Operation**

There are four kinds of reset: external, power-on, watchdog expiration, and software force. The RSTSTA register indicates the source of the last reset, and RSTCLR allows clearing of the RSTSTA register. These registers can be used during a reset exception service routine to identify the source of the reset. If RSTSTA is null, the reset is external.

**Table 44. REMAP Register**

Name	Address	Default Value	Access
REMAP	0xFFFF0220	0xXX <sup>1</sup>	R/W

<sup>1</sup> Depends on the model.

**Table 45. REMAP MMR Bit Designations**

Bit	Name	Description
4	Remap	Read-only bit. Indicates the size of the Flash/EE memory available. If this bit is set, only 32 kB of Flash/EE memory is available.
3		Read-only bit. Indicates the size of the SRAM memory available. If this bit is set, only 4 kB of SRAM is available.
2:1		Reserved.
0		Remap bit. Set by user to remap the SRAM to Address 0x00000000. Cleared automatically after reset to remap the Flash/EE memory to Address 0x00000000.

**Table 46. RSTSTA Register**

Name	Address	Default Value	Access
RSTSTA	0xFFFF0230	0x01	R/W

**Table 47. RSTSTA MMR Bit Designations**

Bit	Description
7:3	Reserved.
2	Software reset. Set by user to force a software reset. Cleared by setting the corresponding bit in RSTCLR.
1	Watchdog timeout. Set automatically when a watchdog timeout occurs. Cleared by setting the corresponding bit in RSTCLR.
0	Power-on reset. Set automatically when a power-on reset occurs. Cleared by setting the corresponding bit in RSTCLR.

**Table 48. RSTCLR Register**

Name	Address	Default Value	Access
RSTCLR	0xFFFF0234	0x00	W

Note that to clear the RSTSTA register, the user must write 0x07 to the RSTCLR register.

**Example source code**

```

t2val_old= T2VAL;
T2LD = 5;
TCON = 0x480;

while ((T2VAL == t2val_old) || (T2VAL >
3)) //ensures timer value loaded
    IRQEN = 0x10;
//enable T2 interrupt
PLLKEY1 = 0xAA;
PLLCON = 0x01;
PLLKEY2 = 0x55;

POWKEY1 = 0x01;
POWCON = 0x27;
// Set Core into Nap mode
POWKEY2 = 0xF4;

```

In noisy environments, noise can couple to the external crystal pins, and PLL may lose lock momentarily. A PLL interrupt is provided in the interrupt controller. The core clock is immediately halted, and this interrupt is only serviced when the lock is restored.

In case of crystal loss, the watchdog timer should be used. During initialization, a test on the RSTSTA register can determine if the reset came from the watchdog timer.

**External Clock Selection**

To switch to an external clock on P0.7, configure P0.7 in Mode 1. The external clock can be up to 44 MHz, providing the tolerance is 1%.

**Table 57. Operating Modes<sup>1</sup>**

Mode	Core	Peripherals	PLL	XTAL/T2/T3	IRQ0 to IRQ3	Start-Up/Power-On Time
Active	X	X	X	X	X	130 ms at CD = 0
Pause		X	X	X	X	24 ns at CD = 0; 3 μs at CD = 7
Nap			X	X	X	24 ns at CD = 0; 3 μs at CD = 7
Sleep				X	X	1.58 ms
Stop					X	1.7 ms

<sup>1</sup> X indicates that the part is powered on.

**Table 58. Typical Current Consumption at 25°C in Milliampere**

PC[2:0]	Mode	CD = 0	CD = 1	CD = 2	CD = 3	CD = 4	CD = 5	CD = 6	CD = 7
000	Active	33.1	21.2	13.8	10	8.1	7.2	6.7	6.45
001	Pause	22.7	13.3	8.5	6.1	4.9	4.3	4	3.85
010	Nap	3.8	3.8	3.8	3.8	3.8	3.8	3.8	3.8
011	Sleep	0.4	0.4	0.4	0.4	0.4	0.4	0.4	0.4
100	Stop	0.4	0.4	0.4	0.4	0.4	0.4	0.4	0.4

**Example source code**

```

t2val_old= T2VAL;
T2LD = 5;
TCON = 0x480;

while ((T2VAL == t2val_old) || (T2VAL >
3)) //ensures timer value loaded
    IRQEN = 0x10;
//enable T2 interrupt
PLLKEY1 = 0xAA;
PLLCON = 0x03; //Select external clock
PLLKEY2 = 0x55;

POWKEY1 = 0x01;
POWCON = 0x27;
// Set Core into Nap mode
POWKEY2 = 0xF4;

```

**Power Control System**

A choice of operating modes is available on the ADuC7019/20/21/22/24/25/26/27/28/29. Table 57 describes what part is powered on in the different modes and indicates the power-up time.

Table 58 gives some typical values of the total current consumption (analog + digital supply currents) in the different modes, depending on the clock divider bits. The ADC is turned off. Note that these values also include current consumption of the regulator and other parts on the test board where these values are measured.

Both switching edges are moved by an equal amount ( $PWMDAT1 \times t_{CORE}$ ) to preserve the symmetrical output patterns.

Also shown are the PWMSYNC pulse and Bit 0 of the PWMSTA register, which indicates whether operation is in the first or second half cycle of the PWM period.

The resulting on times of the PWM signals over the full PWM period (two half periods) produced by the timing unit can be written as follows:

On the high side

$$t_{0HH} = PWMDAT0 + 2(PWMCH0 - PWMDAT1) \times t_{CORE}$$

$$t_{0HL} = PWMDAT0 - 2(PWMCH0 - PWMDAT1) \times t_{CORE}$$

and the corresponding duty cycles ( $d$ )

$$d_{0H} = t_{0HH}/t_s = \frac{1}{2} + (PWMCH0 - PWMDAT1)/PWMDAT0$$

and on the low side

$$t_{0LH} = PWMDAT0 - 2(PWMCH0 + PWMDAT1) \times t_{CORE}$$

$$t_{0LL} = PWMDAT0 + 2(PWMCH0 + PWMDAT1) \times t_{CORE}$$

and the corresponding duty cycles ( $d$ )

$$d_{0L} = t_{0LH}/t_s = \frac{1}{2} - (PWMCH0 + PWMDAT1)/PWMDAT0$$

The minimum permissible  $t_{0H}$  and  $t_{0L}$  values are zero, corresponding to a 0% duty cycle. In a similar fashion, the maximum value is  $t_s$ , corresponding to a 100% duty cycle.

Figure 70 shows the output signals from the timing unit for operation in double update mode. It illustrates a general case where the switching frequency, dead time, and duty cycle are all changed in the second half of the PWM period. The same value for any or all of these quantities can be used in both halves of the PWM cycle. However, there is no guarantee that symmetrical PWM signals are produced by the timing unit in double update mode. Figure 70 also shows that the dead time insertions into the PWM signals are done in the same way as in single update mode.

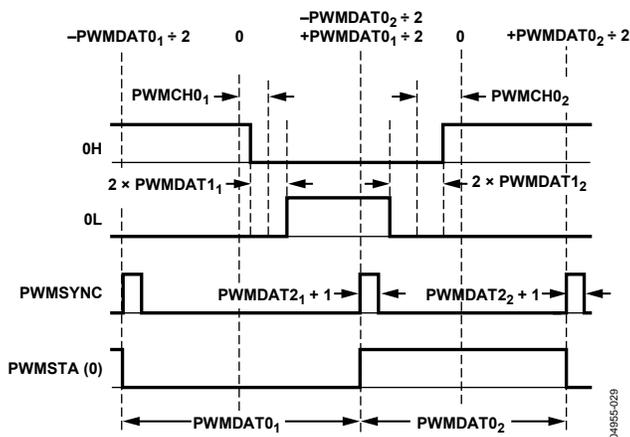


Figure 70. Typical PWM Outputs of the 3-Phase Timing Unit (Double Update Mode)

In general, the on times of the PWM signals in double update mode can be defined as follows:

On the high side

$$t_{0HH} = (PWMDAT0_1/2 + PWMDAT0_2/2 + PWMCH0_1 + PWMCH0_2 - PWMDAT1_1 - PWMDAT1_2) \times t_{CORE}$$

$$t_{0HL} = (PWMDAT0_1/2 + PWMDAT0_2/2 - PWMCH0_1 - PWMCH0_2 + PWMDAT1_1 + PWMDAT1_2) \times t_{CORE}$$

where Subscript 1 refers to the value of that register during the first half cycle, and Subscript 2 refers to the value during the second half cycle.

The corresponding duty cycles ( $d$ ) are

$$d_{0H} = t_{0HH}/t_s = (PWMDAT0_1/2 + PWMDAT0_2/2 + PWMCH0_1 + PWMCH0_2 - PWMDAT1_1 - PWMDAT1_2)/(PWMDAT0_1 + PWMDAT0_2)$$

On the low side

$$t_{0LH} = (PWMDAT0_1/2 + PWMDAT0_2/2 + PWMCH0_1 + PWMCH0_2 + PWMDAT1_1 + PWMDAT1_2) \times t_{CORE}$$

$$t_{0LL} = (PWMDAT0_1/2 + PWMDAT0_2/2 - PWMCH0_1 - PWMCH0_2 - PWMDAT1_1 - PWMDAT1_2) \times t_{CORE}$$

where Subscript 1 refers to the value of that register during the first half cycle, and Subscript 2 refers to the value during the second half cycle.

The corresponding duty cycles ( $d$ ) are

$$d_{0L} = t_{0LH}/t_s = (PWMDAT0_1/2 + PWMDAT0_2/2 + PWMCH0_1 + PWMCH0_2 + PWMDAT1_1 + PWMDAT1_2)/(PWMDAT0_1 + PWMDAT0_2)$$

For the completely general case in double update mode (see Figure 70), the switching period is given by

$$t_s = (PWMDAT0_1 + PWMDAT0_2) \times t_{CORE}$$

Again, the values of  $t_{0H}$  and  $t_{0L}$  are constrained to lie between zero and  $t_s$ .

PWM signals similar to those illustrated in Figure 69 and Figure 70 can be produced on the 1H, 1L, 2H, and 2L outputs by programming the PWMCH1 and PWMCH2 registers in a manner identical to that described for PWMCH0. The PWM controller does not produce any PWM outputs until all of the PWMDAT0, PWMCH0, PWMCH1, and PWMCH2 registers have been written to at least once. When these registers are written, internal counting of the timers in the 3-phase timing unit is enabled.

Writing to the PWMDAT0 register starts the internal timing of the main PWM timer. Provided that the PWMDAT0 register is written to prior to the PWMCH0, PWMCH1, and PWMCH2 registers in the initialization, the first PWMSYNC pulse and interrupt (if enabled) appear  $1.5 \times t_{CORE} \times PWMDAT0$  seconds after the initial write to the PWMDAT0 register in single update mode. In double update mode, the first PWMSYNC pulse appears after  $PWMDAT0 \times t_{CORE}$  seconds.

**Output Control Unit**

The operation of the output control unit is controlled by the 9-bit read/write PWMEN register. This register controls two distinct features of the output control unit that are directly useful in the control of electronic counter measures (ECM) or binary decimal counter measures (BDCM). The PWMEN register contains three crossover bits, one for each pair of PWM outputs. Setting Bit 8 of the PWMEN register enables the crossover mode for the 0H/0L pair of PWM signals, setting Bit 7 enables crossover on the 1H/1L pair of PWM signals, and setting Bit 6 enables crossover on the 2H/2L pair of PWM signals. If crossover mode is enabled for any pair of PWM signals, the high-side PWM signal from the timing unit (0H, for example) is diverted to the associated low-side output of the output control unit so that the signal ultimately appears at the PWM0<sub>L</sub> pin. Of course, the corresponding low-side output of the timing unit is also diverted to the complementary high-side output of the output control unit so that the signal appears at the PWM0<sub>H</sub> pin. Following a reset, the three crossover bits are cleared, and the crossover mode is disabled on all three pairs of PWM signals. The PWMEN register also contains six bits (Bit 0 to Bit 5) that can be used to individually enable or disable each of the six PWM outputs. If the associated bit of the PWMEN register is set, the corresponding PWM output is disabled regardless of the corresponding value of the duty cycle register. This PWM output signal remains in the off state as long as the corresponding enable/disable bit of the PWMEN register is set. The implementation of this output enable function is implemented after the crossover function.

Following a reset, all six enable bits of the PWMEN register are cleared, and all PWM outputs are enabled by default. In a manner identical to the duty cycle registers, the PWMEN is latched on the rising edge of the PWMSYNC signal. As a result, changes to this register become effective only at the start of each PWM cycle in single update mode. In double update mode, the PWMEN register can also be updated at the midpoint of the PWM cycle.

In the control of an ECM, only two inverter legs are switched at any time, and often the high-side device in one leg must be switched on at the same time as the low-side driver in a second leg. Therefore, by programming identical duty cycle values for two PWM channels (for example, PWMCH0 = PWMCH1) and setting Bit 7 of the PWMEN register to cross over the 1H/1L pair of PWM signals, it is possible to turn on the high-side switch of Phase A and the low-side switch of Phase B at the same time. In the control of ECM, it is usual for the third inverter leg (Phase C in this example) to be disabled for a number of PWM cycles. This function is implemented by disabling both the 2H and 2L PWM outputs by setting Bit 0 and Bit 1 of the PWMEN register.

This situation is illustrated in Figure 71, where it can be seen that both the 0H and 1L signals are identical because PWMCH0 = PWMCH1 and the crossover bit for Phase B is set.

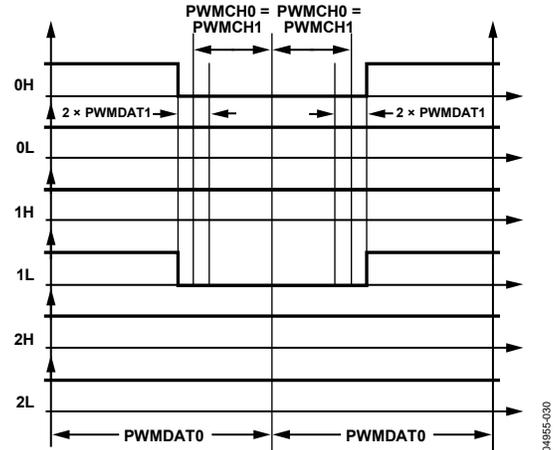


Figure 71. Active Low PWM Signals Suitable for ECM Control, PWMCH0 = PWMCH1, Crossover 1H/1L Pair and Disable 0L, 1H, 2H, and 2L Outputs in Single Update Mode.

In addition, the other four signals (0L, 1H, 2H, and 2L) have been disabled by setting the appropriate enable/disable bits of the PWMEN register. In Figure 71, the appropriate value for the PWMEN register is 0x00A7. In normal ECM operation, each inverter leg is disabled for certain periods of time to change the PWMEN register based on the position of the rotor shaft (motor commutation).

**Gate Drive Unit**

The gate drive unit of the PWM controller adds features that simplify the design of isolated gate-drive circuits for PWM inverters. If a transformer-coupled, power device, gate-drive amplifier is used, the active PWM signal must be chopped at a high frequency. The 16-bit read/write PWMCFG register programs this high frequency chopping mode. The chopped active PWM signals can be required for the high-side drivers only, the low-side drivers only, or both the high-side and low-side switches. Therefore, independent control of this mode for both high-side and low-side switches is included with two separate control bits in the PWMCFG register.

Typical PWM output signals with high frequency chopping enabled on both high-side and low-side signals are shown in Figure 72. Chopping of the high-side PWM outputs (0H, 1H, and 2H) is enabled by setting Bit 8 of the PWMCFG register. Chopping of the low-side PWM outputs (0L, 1L, and 2L) is enabled by setting Bit 9 of the PWMCFG register. The high chopping frequency is controlled by the 8-bit word (GDCLK) placed in Bit 0 to Bit 7 of the PWMCFG register. The period of this high frequency carrier is

$$t_{CHOP} = (4 \times (GDCLK + 1)) \times t_{CORE}$$

The chopping frequency is, therefore, an integral subdivision of the MicroConverter core frequency

$$f_{CHOP} = f_{CORE} / (4 \times (GDCLK + 1))$$

Table 116. COMIID1 MMR Bit Descriptions

Bit 3:1 Status Bits	Bit 0 NINT	Priority	Definition	Clearing Operation
000	1		No interrupt	
110	0	2	Matching network address	Read COMRX
101	0	3	Address transmitted, buffer empty	Write data to COMTX or read COMIID0
011	0	1	Receive line status interrupt	Read COMSTA0
010	0	2	Receive buffer full interrupt	Read COMRX
001	0	3	Transmit buffer empty interrupt	Write data to COMTX or read COMIID0
000	0	4	Modem status interrupt	Read COMSTA1

Note that to receive a network address interrupt, the slave must ensure that Bit 0 of COMIEN0 (enable receive buffer full interrupt) is set to 1.

Table 117. COMADR Register

Name	Address	Default Value	Access
COMADR	0xFFFF0728	0xAA	R/W

COMADR is an 8-bit, read/write network address register that holds the address checked for by the network addressable UART. Upon receiving this address, the device interrupts the processor and/or sets the appropriate status bit in COMIID1.

**SERIAL PERIPHERAL INTERFACE**

The ADuC7019/20/21/22/24/25/26/27/28/29 integrate a complete hardware serial peripheral interface (SPI) on-chip. SPI is an industry standard, synchronous serial interface that allows eight bits of data to be synchronously transmitted and simultaneously received, that is, full duplex up to a maximum bit rate of 3.48 Mb, as shown in Table 118. The SPI interface is not operational with core clock divider (CD) bits. POWCON[2:0] = 6 or 7 in master mode.

The SPI port can be configured for master or slave operation, and typically consists of four pins: MISO (P1.5), MOSI (P1.6), SCLK (P1.4), and CS (P1.7).

On the transmit side, the SPITX register (and a TX shift register outside it) loads data onto the transmit pin (in slave mode, MISO; in master mode, MOSI). The transmit status bit, Bit 0, in SPISTA indicates whether there is valid data in the SPITX register.

Similarly, the receive data path consists of the SPIRX register (and an RX shift register). SPISTA, Bit 3 indicates whether there is valid data in the SPIRX register. If valid data in the SPIRX register is overwritten or if valid data in the RX shift register is discarded, SPISTA, Bit 5 (the overflow bit) is set.

**MISO (Master In, Slave Out) Pin**

The MISO pin is configured as an input line in master mode and an output line in slave mode. The MISO line on the master (data in) should be connected to the MISO line in the slave device (data out). The data is transferred as byte wide (8-bit) serial data, MSB first.

**MOSI (Master Out, Slave In) Pin**

The MOSI pin is configured as an output line in master mode and an input line in slave mode. The MOSI line on the master (data out) should be connected to the MOSI line in the slave device (data in). The data is transferred as byte wide (8-bit) serial data, MSB first.

**SCLK (Serial Clock I/O) Pin**

The master serial clock (SCLK) is used to synchronize the data being transmitted and received through the MOSI SCLK period. Therefore, a byte is transmitted/received after eight SCLK periods. The SCLK pin is configured as an output in master mode and as an input in slave mode.

In master mode, the polarity and phase of the clock are controlled by the SPICON register, and the bit rate is defined in the SPIDIV register as follows:

$$f_{SERIALCLOCK} = \frac{f_{UCLK}}{2 \times (1 + SPIDIV)}$$

The maximum speed of the SPI clock is dependent on the clock divider bits and is summarized in Table 118.

Table 118. SPI Speed vs. Clock Divider Bits in Master Mode

CD Bits	0	1	2	3	4	5
SPIDIV in Hex	0x05	0x0B	0x17	0x2F	0x5F	0xBF
SPI speed in MHz	3.482	1.741	0.870	0.435	0.218	0.109

In slave mode, the SPICON register must be configured with the phase and polarity of the expected input clock. The slave accepts data from an external master up to 10.4 Mb at CD = 0. The formula to determine the maximum speed is as follows:

$$f_{SERIALCLOCK} = \frac{f_{HCLK}}{4}$$

In both master and slave modes, data is transmitted on one edge of the SCL signal and sampled on the other. Therefore, it is important that the polarity and phase be configured the same for the master and slave devices.

**Chip Select (CS Input) Pin**

In SPI slave mode, a transfer is initiated by the assertion of CS, which is an active low input signal. The SPI port then transmits and receives 8-bit data until the transfer is concluded by deassertion of CS. In slave mode, CS is always an input.

**SPI Registers**

The following MMR registers are used to control the SPI interface: SPISTA, SPIRX, SPITX, SPIDIV, and SPICON.

**Table 119. SPISTA Register**

Name	Address	Default Value	Access
SPISTA	0xFFFF0A00	0x00	R

SPISTA is an 8-bit read-only status register. Only Bit 1 or Bit 4 of this register generates an interrupt. Bit 6 of the SPICON register determines which bit generates the interrupt.

**Table 120. SPISTA MMR Bit Descriptions**

Bit	Description
7:6	Reserved.
5	SPIRX data register overflow status bit. Set if SPIRX is overflowing. Cleared by reading the SPIRX register.
4	SPIRX data register IRQ. Set automatically if Bit 3 or Bit 5 is set. Cleared by reading the SPIRX register.
3	SPIRX data register full status bit. Set automatically if a valid data is present in the SPIRX register. Cleared by reading the SPIRX register.
2	SPITX data register underflow status bit. Set automatically if SPITX is underflowing. Cleared by writing in the SPITX register.
1	SPITX data register IRQ. Set automatically if Bit 0 is clear or Bit 2 is set. Cleared by writing in the SPITX register or if finished transmission disabling the SPI.
0	SPITX data register empty status bit. Set by writing to SPITX to send data. This bit is set during transmission of data. Cleared when SPITX is empty.

**Table 125. SPICON MMR Bit Descriptions**

Bit	Description	Function
15:13	Reserved	N/A
12	Continuous transfer enable	Set by user to enable continuous transfer. In master mode, the transfer continues until no valid data is available in the TX register. $\overline{CS}$ is asserted and remains asserted for the duration of each 8-bit serial transfer until TX is empty. Cleared by user to disable continuous transfer. Each transfer consists of a single 8-bit serial transfer. If valid data exists in the SPITX register, then a new transfer is initiated after a stall period.
11	Loop back enable	Set by user to connect MISO to MOSI and test software. Cleared by user to be in normal mode.
10	Slave MISO output enable	Set this bit to disable the output driver on the MISO pin. The MISO pin becomes open drain when this bit is set. Clear this bit for MISO to operate as normal.
9	Clip select output enable	Set by user in master mode to disable the chip select output. Cleared by user to enable the chip select output. P1.7 should be configured as $\overline{CS}$ before SPICON is configured as a master when the chip select output enabled is also selected.
8	SPIRX overflow overwrite enable	Set by user, the valid data in the RX register is overwritten by the new serial byte received. Cleared by user, the new serial byte received is discarded.
7	SPITX underflow mode	Set by user to transmit 0. Cleared by user to transmit the previous data.
6	Transfer and interrupt mode	Set by user to initiate transfer with a write to the SPITX register. Interrupt occurs only when TX is empty. Cleared by user to initiate transfer with a read of the SPIRX register. Interrupt occurs only when RX is full.
5	LSB first transfer enable bit	Set by user, the LSB is transmitted first. Cleared by user, the MSB is transmitted first.
4	Reserved	
3	Serial clock polarity mode bit	Set by user, the serial clock idles high. Cleared by user, the serial clock idles low.
2	Serial clock phase mode bit	Set by user, the serial clock pulses at the beginning of each serial bit transfer. Cleared by user, the serial clock pulses at the end of each serial bit transfer.
1	Master mode enable bit	Set by user to enable master mode. Cleared by user to enable slave mode.
0	SPI enable bit	Set by user to enable the SPI. Cleared by user to disable the SPI.

**Table 121. SPIRX Register**

Name	Address	Default Value	Access
SPIRX	0xFFFF0A04	0x00	R

SPIRX is an 8-bit, read-only receive register.

**Table 122. SPITX Register**

Name	Address	Default Value	Access
SPITX	0xFFFF0A08	0x00	W

SPITX is an 8-bit, write-only transmit register.

**Table 123. SPIDIV Register**

Name	Address	Default Value	Access
SPIDIV	0xFFFF0A0C	0x1B	R/W

SPIDIV is an 8-bit, serial clock divider register.

**Table 124. SPICON Register**

Name	Address	Default Value	Access
SPICON	0xFFFF0A10	0x0000	R/W

SPICON is a 16-bit control register.

Table 140. I2CxDIV Registers

Name	Address	Default Value	Access
I2C0DIV	0xFFFF0830	0x1F1F	R/W
I2C1DIV	0xFFFF0930	0x1F1F	R/W

I2CxDIV are the clock divider registers.

Table 141. I2CxIDx Registers

Name	Address	Default Value	Access
I2C0ID0	0xFFFF0838	0x00	R/W
I2C0ID1	0xFFFF083C	0x00	R/W
I2C0ID2	0xFFFF0840	0x00	R/W
I2C0ID3	0xFFFF0844	0x00	R/W
I2C1ID0	0xFFFF0938	0x00	R/W
I2C1ID1	0xFFFF093C	0x00	R/W
I2C1ID2	0xFFFF0940	0x00	R/W
I2C1ID3	0xFFFF0944	0x00	R/W

I2CxID0, I2CxID1, I2CxID2, and I2CxID3 are slave address device ID registers of I2Cx.

Table 142. I2CxCCNT Registers

Name	Address	Default Value	Access
I2C0CCNT	0xFFFF0848	0x01	R/W
I2C1CCNT	0xFFFF0948	0x01	R/W

I2CxCCNT are 8-bit start/stop generation counters. They hold off SDA low for start and stop conditions.

Table 143. I2CxFSTA Registers

Name	Address	Default Value	Access
I2C0FSTA	0xFFFF084C	0x0000	R/W
I2C1FSTA	0xFFFF094C	0x0000	R/W

I2CxFSTA are FIFO status registers.

Table 144. I2C0FSTA MMR Bit Descriptions

Bit	Access Type	Value	Description
15:10			Reserved.
9	R/W		Master transmit FIFO flush. Set by the user to flush the master Tx FIFO. Cleared automatically when the master Tx FIFO is flushed. This bit also flushes the slave receive FIFO.
8	R/W		Slave transmit FIFO flush. Set by the user to flush the slave Tx FIFO. Cleared automatically after the slave Tx FIFO is flushed.
7:6	R	00 01 10 11	Master Rx FIFO status bits. FIFO empty. Byte written to FIFO. One byte in FIFO. FIFO full.
5:4	R	00 01 10 11	Master Tx FIFO status bits. FIFO empty. Byte written to FIFO. One byte in FIFO. FIFO full.
3:2	R	00 01 10 11	Slave Rx FIFO status bits. FIFO empty. Byte written to FIFO. One byte in FIFO. FIFO full.
1:0	R	00 01 10 11	Slave Tx FIFO status bits. FIFO empty. Byte written to FIFO. One byte in FIFO. FIFO full.

**Table 148. PLACLK Register**

Name	Address	Default Value	Access
PLACLK	0xFFFF0B40	0x00	R/W

PLACLK is the clock selection for the flip-flops of Block 0 and Block 1. Note that the maximum frequency when using the GPIO pins as the clock input for the PLA blocks is 44 MHz.

**Table 149. PLACLK MMR Bit Descriptions**

Bit	Value	Description
7		Reserved.
6:4		Block 1 clock source selection.
	000	GPIO clock on P0.5.
	001	GPIO clock on P0.0.
	010	GPIO clock on P0.7.
	011	HCLK.
	100	OCLK (32.768 kHz) external crystal only.
	101	Timer1 overflow.
	Other	Reserved.
3		Reserved.
2:0		Block 0 clock source selection.
	000	GPIO clock on P0.5.
	001	GPIO clock on P0.0.
	010	GPIO clock on P0.7.
	011	HCLK.
	100	OCLK (32.768 kHz) external crystal only.
	101	Timer1 overflow.
	Other	Reserved.

**Table 152. Feedback Configuration**

Bit	Value	PLAELM0	PLAELM1 to PLAELM7	PLAELM8	PLAELM9 to PLAELM15
10:9	00	Element 15	Element 0	Element 7	Element 8
	01	Element 2	Element 2	Element 10	Element 10
	10	Element 4	Element 4	Element 12	Element 12
	11	Element 6	Element 6	Element 14	Element 14
8:7	00	Element 1	Element 1	Element 9	Element 9
	01	Element 3	Element 3	Element 11	Element 11
	10	Element 5	Element 5	Element 13	Element 13
	11	Element 7	Element 7	Element 15	Element 15

**Table 150. PLAIRQ Register**

Name	Address	Default Value	Access
PLAIRQ	0xFFFF0B44	0x00000000	R/W

PLAIRQ enables IRQ0 and/or IRQ1 and selects the source of the IRQ.

**Table 151. PLAIRQ MMR Bit Descriptions**

Bit	Value	Description
15:13		Reserved.
12		PLA IRQ1 enable bit. Set by user to enable IRQ1 output from PLA. Cleared by user to disable IRQ1 output from PLA.
11:8		PLA IRQ1 source.
	0000	PLA Element 0.
	0001	PLA Element 1.
	1111	PLA Element 15.
7:5		Reserved.
4		PLA IRQ0 enable bit. Set by user to enable IRQ0 output from PLA. Cleared by user to disable IRQ0 output from PLA.
3:0		PLA IRQ0 source.
	0000	PLA Element 0.
	0001	PLA Element 1.
	1111	PLA Element 15.

In normal mode, an IRQ is generated each time the value of the counter reaches zero when counting down. It is also generated each time the counter value reaches full scale when counting up. An IRQ can be cleared by writing any value to clear the register of that particular timer (TxCLRI).

When using an asynchronous clock-to-clock timer, the interrupt in the timer block may take more time to clear than the time it takes for the code in the interrupt routine to execute. Ensure that the interrupt signal is cleared before leaving the interrupt service routine. This can be done by checking the IRQSTA MMR.

**Hour:Minute:Second:1/128 Format**

To use the timer in hour:minute:second:hundredths format, select the 32,768 kHz clock and prescaler of 256. The hundredths field does not represent milliseconds but 1/128 of a second (256/32,768). The bits representing the hour, minute, and second are not consecutive in the register. This arrangement applies to TxLD and TxVAL when using the hour:minute:second:hundredths format as set in TxCON[5:4]. See Table 171 for additional details.

**Table 171. Hour:Minute:Second:Hundredths Format**

Bit	Value	Description
31:24	0 to 23 or 0 to 255	Hours
23:22	0	Reserved
21:16	0 to 59	Minutes
15:14	0	Reserved
13:8	0 to 59	Seconds
7	0	Reserved
6:0	0 to 127	1/128 second

**Timer0 (RTOS Timer)**

Timer0 is a general-purpose, 16-bit timer (count down) with a programmable prescaler (see Figure 77). The prescaler source is the core clock frequency (HCLK) and can be scaled by factors of 1, 16, or 256.

Timer0 can be used to start ADC conversions as shown in the block diagram in Figure 77.

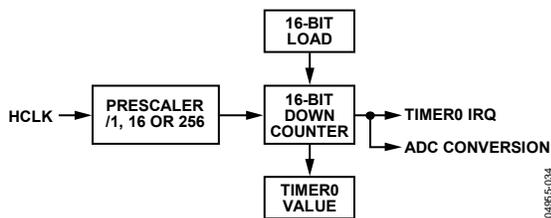


Figure 77. Timer0 Block Diagram

The Timer0 interface consists of four MMRs: T0LD, T0VAL, T0CON, and T0CLRI.

**Table 172. T0LD Register**

Name	Address	Default Value	Access
T0LD	0xFFFF0300	0x0000	R/W

T0LD is a 16-bit load register.

**Table 173. T0VAL Register**

Name	Address	Default Value	Access
T0VAL	0xFFFF0304	0xFFFF	R

T0VAL is a 16-bit read-only register representing the current state of the counter.

**Table 174. T0CON Register**

Name	Address	Default Value	Access
T0CON	0xFFFF0308	0x0000	R/W

T0CON is the configuration MMR described in Table 175.

**Table 175. T0CON MMR Bit Descriptions**

Bit	Value	Description
15:8		Reserved.
7		Timer0 enable bit. Set by user to enable Timer0. Cleared by user to disable Timer0 by default.
6		Timer0 mode. Set by user to operate in periodic mode. Cleared by user to operate in free-running mode. Default mode.
5:4		Reserved.
3:2		Prescale.
	00	Core Clock/1. Default value.
	01	Core Clock/16.
	10	Core Clock/256.
	11	Undefined. Equivalent to 00.
1:0		Reserved.

**Table 176. T0CLRI Register**

Name	Address	Default Value	Access
T0CLRI	0xFFFF030C	0xFF	W

T0CLRI is an 8-bit register. Writing any value to this register clears the interrupt.

**Table 180. T1CON MMR Bit Descriptions**

Bit	Value	Description
31:18		Reserved.
17		Event select bit. Set by user to enable time capture of an event. Cleared by user to disable time capture of an event.
16:12		Event select range, 0 to 31. These events are as described in Table 160. All events are offset by two; that is, Event 2 in Table 160 becomes Event 0 for the purposes of Timer1.
11:9	000 001 010 011	Clock select. Core clock (HCLK). External 32.768 kHz crystal. P1.0 rising edge triggered. P0.6 rising edge triggered.
8		Count up. Set by user for Timer1 to count up. Cleared by user for Timer1 to count down by default.
7		Timer1 enable bit. Set by user to enable Timer1. Cleared by user to disable Timer1 by default.
6		Timer1 mode. Set by user to operate in periodic mode. Cleared by user to operate in free-running mode. Default mode.
5:4	00 01 10 11	Format. Binary. Reserved. Hr: min: sec: hundredths (23 hours to 0 hour). Hr: min: sec: hundredths (255 hours to 0 hour).
3:0	0000 0100 1000 1111	Prescale. Source Clock/1. Source Clock/16. Source Clock/256. Source Clock/32,768.

**Table 181. T1CLR1 Register**

Name	Address	Default Value	Access
T1CLR1	0xFFFF032C	0xFF	W

T1CLR1 is an 8-bit register. Writing any value to this register clears the Timer1 interrupt.

**Table 182. T1CAP Register**

Name	Address	Default Value	Access
T1CAP	0xFFFF0330	0x00000000	R/W

T1CAP is a 32-bit register. It holds the value contained in T1VAL when a particular event occurs. This event must be selected in T1CON.

**Timer2 (Wake-Up Timer)**

Timer2 is a 32-bit wake-up timer (count down or count up) with a programmable prescaler. The source can be the 32 kHz external crystal, the core clock frequency, or the internal 32 kHz oscillator. The clock source can be scaled by a factor of 1, 16, 256, or 32,768. The wake-up timer continues to run when the core clock is disabled.

The counter can be formatted as plain 32-bit value or as hours: minutes: seconds: hundredths.

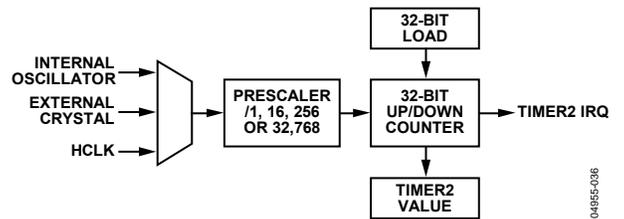


Figure 79. Timer2 Block Diagram

The Timer2 interface consists of four MMRs: T2LD, T2VAL, T2CON, and T2CLR1.

**Table 183. T2LD Register**

Name	Address	Default Value	Access
T2LD	0xFFFF0340	0x00000000	R/W

T2LD is a 32-bit register load register.

**Table 184. T2VAL Register**

Name	Address	Default Value	Access
T2VAL	0xFFFF0344	0xFFFFFFFF	R

T2VAL is a 32-bit read-only register that represents the current state of the counter.

**Table 185. T2CON Register**

Name	Address	Default Value	Access
T2CON	0xFFFF0348	0x0000	R/W

T2CON is the configuration MMR described in Table 186.

# HARDWARE DESIGN CONSIDERATIONS

## POWER SUPPLIES

The ADuC7019/20/21/22/24/25/26/27/28/29 operational power supply voltage range is 2.7 V to 3.6 V. Separate analog and digital power supply pins ( $AV_{DD}$  and  $IOV_{DD}$ , respectively) allow  $AV_{DD}$  to be kept relatively free of noisy digital signals often present on the system  $IOV_{DD}$  line. In this mode, the part can also operate with split supplies; that is, it can use different voltage levels for each supply. For example, the system can be designed to operate with an  $IOV_{DD}$  voltage level of 3.3 V whereas the  $AV_{DD}$  level can be at 3 V or vice versa. A typical split supply configuration is shown in Figure 87.

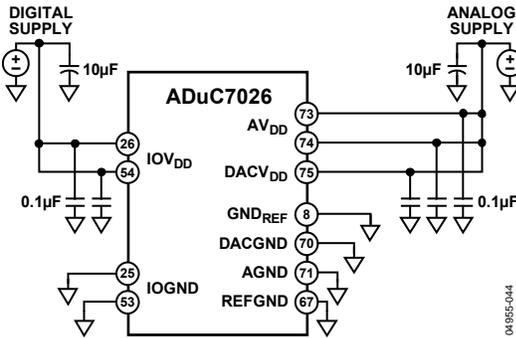


Figure 87. External Dual Supply Connections

As an alternative to providing two separate power supplies, the user can reduce noise on  $AV_{DD}$  by placing a small series resistor and/or ferrite bead between  $AV_{DD}$  and  $IOV_{DD}$  and then decoupling  $AV_{DD}$  separately to ground. An example of this configuration is shown in Figure 88. With this configuration, other analog circuitry (such as op amps and voltage reference) can be powered from the  $AV_{DD}$  supply line as well.

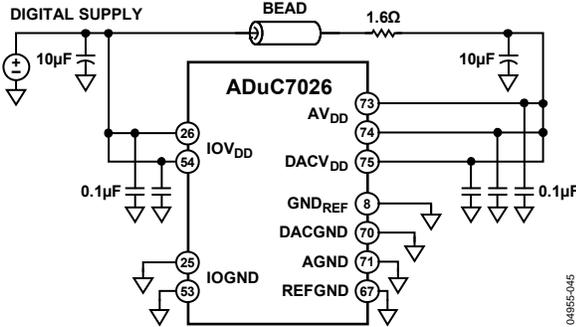


Figure 88. External Single Supply Connections

Note that in both Figure 87 and Figure 88, a large value (10 µF) reservoir capacitor sits on  $IOV_{DD}$ , and a separate 10 µF capacitor sits on  $AV_{DD}$ . In addition, local small-value (0.1 µF) capacitors are located at each  $AV_{DD}$  and  $IOV_{DD}$  pin of the chip. As per standard design practice, be sure to include all of these capacitors and ensure that the smaller capacitors are close to each  $AV_{DD}$  pin with trace lengths as short as possible. Connect the ground terminal of each of these capacitors directly to the underlying ground plane.

Finally, note that the analog and digital ground pins on the ADuC7019/20/21/22/24/25/26/27/28/29 must be referenced to the same system ground reference point at all times.

## IOV<sub>DD</sub> Supply Sensitivity

The  $IOV_{DD}$  supply is sensitive to high frequency noise because it is the supply source for the internal oscillator and PLL circuits. When the internal PLL loses lock, the clock source is removed by a gating circuit from the CPU, and the ARM7TDMI core stops executing code until the PLL regains lock. This feature ensures that no flash interface timings or ARM7TDMI timings are violated.

Typically, frequency noise greater than 50 kHz and 50 mV p-p on top of the supply causes the core to stop working.

If decoupling values recommended in the Power Supplies section do not sufficiently dampen all noise sources below 50 mV on  $IOV_{DD}$ , a filter such as the one shown in Figure 89 is recommended.

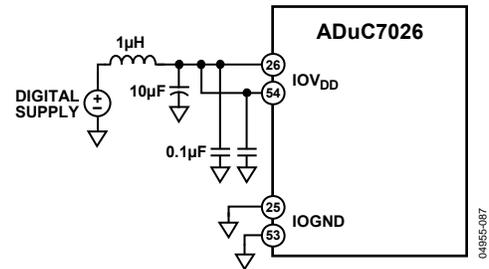


Figure 89. Recommended  $IOV_{DD}$  Supply Filter

## Linear Voltage Regulator

Each ADuC7019/20/21/22/24/25/26/27/28/29 requires a single 3.3 V supply, but the core logic requires a 2.6 V supply. An on-chip linear regulator generates the 2.6 V from  $IOV_{DD}$  for the core logic. The  $LV_{DD}$  pin is the 2.6 V supply for the core logic. An external compensation capacitor of 0.47 µF must be connected between  $LV_{DD}$  and  $DGND$  (as close as possible to these pins) to act as a tank of charge as shown in Figure 90.

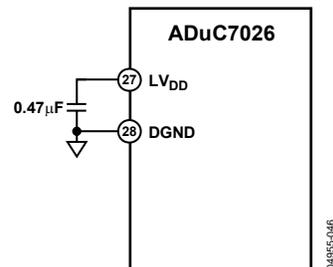


Figure 90. Voltage Regulator Connections

The  $LV_{DD}$  pin should not be used for any other chip. It is also recommended to use excellent power supply decoupling on  $IOV_{DD}$  to help improve line regulation performance of the on-chip voltage regulator.